| PCN Nu | ımher | 201503100 | 20150310000 | | | | | • | 03/20/2015 | |
|--|---------------------------|----------------|--------------------|----------------|----------------------|--------------------|---------------------|---------------------|------------|--|
| Title: Datasheet update for BQ2 | | | | 70 | PCN Date | | 03/20/2013 | | | |
| | | PCN Manager | | | pt: Quality Services | | | | | |
| Change | | - I or manager | | Бери | - Quality t | JC: V:C | | | | |
| | sembly Site | | | Design | | | Wafer B | um | n Site | |
| | Assembly Process | | X | | | | | Wafer Bump Material | | |
| Assembly Materials | | Ħ | Part number change | | _ | Wafer Bump Process | | | | |
| Mechanical Specification | | Ī | Test Site | | | | Wafer Fab Site | | | |
| Packing/Shipping/Labeling | | | Test Proces | est Process | | Wafer F | Wafer Fab Materials | | | |
| | | | | | | | Wafer Fab Process | | | |
| PCN Details | | | | | | | | | | |
| Description of Change: | | | | | | | | | | |
| Texas Instruments Incorporated is announcing an information only notification. | | | | | | | | | | |
| | | | | | | | | | | |
| The product datasheet(s) is being updated as summarized below. | | | | | | | | | | |
| The following change history provides further details | | | | | | | | | | |
| THE TOIL | owning change i | nscory provid | C5 1 | artifici actai | 13 | | | | | |
| | | | | | | | √ Ü | ŢE | XAS | |
| bq25570 | | | | | | | | | | |
| SLUSBH2E – MARCH 2013 – REVISED MARCH 2015 www.ti.com | | | | | | | | | | |
| Changes from Revision D (December 2014) to Revision E Page | | | | | | | | | | |
| Changed the Test Condition for P _{IN(CS)} in the <i>Electrical Characteristics</i> 6 | | | | | | | | | | |
| Changed the values for P _{IN(CS)} in the <i>Electrical Characteristics</i> From: TYP = 5 To: TYP = 15 | | | | | | | | | | |
| • Changed CBYP = 0.1 µF To: CBYP = 0.01 µF in Detailed Design Procedure | | | | | | | | 24 | | |
| • Changed CBYP = 0.1 µF To: CBYP = 0.01 µF in Detailed Design Procedure | | | | | | | | 27 | | |
| • Changed CBYP = 0.1 µF To: CBYP = 0.01 µF in Detailed Design Procedure | | | | | | | | 30 | | |
| | | | | | | | | | | |
| | | | | | | | | | | |
| | asheet number | | | | | Class | | | | |
| | | | | nge From: | ange To: | | | | | |
| BQ255 | BQ25570 SLUSBH2D SLUSBH2E | | | | | | | | | |
| | | | | | | | | | | |
| These changes may be reviewed at the datasheet links provided. | | | | | | | | | | |
| http://www.ti.com/product/bq25570 | | | | | | | | | | |
| Reason for Change: | | | | | | | | | | |
| To more accurately reflect device characteristics. | | | | | | | | | | |
| Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): | | | | | | | | | | |
| Electrical specification performance changes as indicated above. | | | | | | | | | | |
| Changes to product identification resulting from this PCN: | | | | | | | | | | |
| None. | | | | | | | | | | |
| Produc | t Affected: | | | | | | | | | |
| | | | | BO3EE. | BQ25570RGRT | | | | | |
| DQZ55 | 70RGRR | | | DQ255 | UKGKI | | | | | |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--------------------------------|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |